

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.0078	0.91	0.1183
	Doped silicon	Silicon (Si)	7440-21-3	0.84894	99.09	12.8817
			Subtotal	0.85674	100	13
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.04678	10.0	0.70985
	Silver alloy	Silver (Ag)	7440-22-4	0.00936	2.0	0.14197
	Lead alloy	Lead (Pb)	7439-92-1	0.41167	88.0	6.24666
			Subtotal	0.46781	100	7.09848
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.27734	100.0	4.20829
			Subtotal	0.27734	100	4.20829
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00968	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00646	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00968	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03551	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.21719	99.81	488.8594
			Subtotal	32.27852	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.31963	100.0	4.85
			Subtotal	0.31963	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.264	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.29797	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.4606	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.1974	0.3	2.99532
	Polymer	Epoxy resin system		6.58	10.0	99.844
			Subtotal	65.79997	100	998.44
			Total	100.00001	100	1517.38678

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